

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	SAF-XC836-2FRI AB	**Issued**	29. August 2013
MA#	MA001002902		
Package	PG-TSSOP-28-1	**Weight***	107.13 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.495	4.20	4.20	41960	41960
leadframe	non noble metal	nickel	7440-02-0	14.398	13.44		134392	
	non noble metal	iron	7439-89-6	19.882	18.56	32.00	185589	319981
wire	noble metal	gold	7440-57-5	0.584	0.55	0.55	5451	5451
encapsulation	organic material	carbon black	1333-86-4	0.190	0.18		1776	
	plastics	epoxy resin	-	8.055	7.52		75187	
	inorganic material	silicondioxide	60676-86-0	55.179	51.49	59.19	515059	592022
leadfinish	non noble metal	tin	7440-31-5	1.539	1.44	1.44	14370	14370
plating	noble metal	silver	7440-22-4	1.416	1.32	1.32	13214	13214
glue	plastics	acrylic resin	-	0.279	0.26		2600	
	noble metal	silver	7440-22-4	1.114	1.04	1.30	10402	13002
*deviation	< 10%				Sum in total:	100,00		1000000

Important Remarks:

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